

Abstract of the Disclosure

[0046] This invention relates to an apparatus and method for increasing microelectronic package density by stacking multiple microelectronic packages in an array and controlling package to package scalability without stressing the carrier substrates and without limiting the number of signal and input/output leads. Specifically, an intermediate substrate having conductive risers therein is used to enable pitch control of the package to package interconnection, control of the standoff distance and act as a microelectronic package stiffener.